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Appl. No. 10/791,569

Response to Office Action mailed January 4, 2007

R E M A R K S

The Examiner is respectfully requested to acknowledge applicant's claim for priority under 35 USC 119 and receipt of the certified copy of the priority document.

The Examiner is also respectfully requested to return copies of the Form PTO/SB/08A filed March 1, 2004, the Form PTO/SB/08A filed January 31, 2005 and the Form PTO/SB/08A filed December 5, 2005, and to indicate thereon that the cited publications were considered and made of record.

Restriction was required under 35 USC 121 as follows:

Group I. Claims 1, 4 to 8, 11 to 17, 20 to 25 and 44,  
drawn to metallic material products consisting of  
an alloy including Cu, Mo and elements selected  
from the group consisting of Al, Au, Ag, Ti, Ni,  
Co and Si;

Group II. Claims 2, 9, 18 and 45, drawn to metallic material  
products consisting of a "binary alloy" including  
Cu and Mo;

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Group III. Claims 3, 10, 19 and 46, drawn to metallic material products consisting of an alloy including Cu and elements selected from the group consisting of Cr, Ta, W and Ti and elements selected from the group consisting of Al, Au, Ni, Co and Si;

Group IV. Claims 26, 38 and 41, drawn to a working method for etching metallic material consisting of an alloy including Cu, Mo and elements selected from the group consisting of Al, Au, Ag, Ti, Ni, Co and Si, the steps comprising "solution etching with phosphoric acid and nitric acid" to form a wiring pattern, an electrode, or a contact;

Group V. Claims 27, 39, and 42, drawn to a working method for etching metallic material consisting of a "binary alloy" including Cu and Mo, the steps comprising "solution etching with phosphoric acid and nitric acid" to form a wiring pattern, an electrode, or a contact;

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Group VI. Claims 28, 40, and 43, drawn to a working method for etching metallic material consisting of an alloy including Cu and elements selected from the group consisting of Cr, Ta, W, and Ti and elements selected from the group consisting of Al, Au, Ni, Co, and Si, the steps comprising "solution etching with phosphoric acid and nitric acid" to form a wiring pattern, an electrode, or a contact;

Group VII. Claim 29, drawn to a working method for etching metallic material consisting of an alloy including Cu, Mo, and elements selected from the group consisting of Al, Au, Ag, Ti, Ni, Co, and Si, the steps comprising "gas etching with hydrochloric acid" to form a wiring pattern, an electrode, or a contact;

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Group VIII. Claim 30, drawn to a working method for etching metallic material consisting of a binary alloy including Cu, Mo, the steps comprising "gas etching with hydrochloric acid" to form a wiring pattern, an electrode, or a contact;

Group IX. Claim 31, drawn to a working method for etching metallic material consisting of an alloy including Cu, Mo, and elements selected from the group consisting of Cr, Ta, W, and Ti and elements selected from the group consisting of Al, Au, Ni, Co, and Si, the steps comprising "gas etching with hydrochloric acid" to form a wiring pattern, an electrode, or a contact;

Group X. Claim 32, drawn to a manufacturing method of an electronic component with a metallic film consisting of an alloy including Cu, Mo, and elements selected from the group consisting of Al, Au, Ag, Ti, Ni, Co, and Si, and a film other

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than said metallic film is gas etched under a gas atmosphere including fluorine;

Group XI. Claim 33, drawn to a manufacturing method of an electronic component with a metallic film consisting of a binary alloy including Cu, Mo, and a film other than said metallic film is gas etched under a gas atmosphere including fluorine;

Group XII. Claim 34, drawn to a manufacturing method of an electronic component with a metallic film consisting of an alloy including Cu, Mo, and elements selected from the group consisting of Cr, Ta, W, and Ti and elements selected from the group consisting of Al, Au, Ag, Ti, Ni, Co, and Si, and a film other than said metallic film is gas etched under a gas atmosphere including fluorine;

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Group XIII. Claim 35, drawn to a working method for etching metallic material consisting of an alloy including Cu, Mo, and elements selected from the group consisting of Al, Au, Ag, Ti, Ni, Co, and Si, the steps comprising heat treatment in the range of temperatures from 100°C to 750°C to form a wiring pattern, an electrode, or a contact;

Group XIV. Claim 36, drawn to a working method for etching metallic material consisting of a binary alloy including Cu, Mo, the steps comprising heat treatment in the range of temperatures from 100°C to 750°C to form a wiring pattern, an electrode, or a contact; and

Group XV. Claim 37, drawn to a working method for etching metallic material consisting of an alloy including Cu, Mo, and elements selected from the group consisting of Cr, Ta, W, and Ti and

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elements selected from the group consisting of Al, Au, Ag, Ti, Ni, Co, and Si, the steps comprising a heat treatment in the range of temperatures from 100°C to 750°C to form a wiring pattern, an electrode, or a contact.

Applicant elects Group II (claims 2, 9, 18 and 45, drawn to metallic material products consisting of a "binary alloy" including Cu and Mo).

The Restriction Requirement is traversed in that it was based on 35 USC 372, PCT Rule 13.1 and 37 CFR 1.499, which govern national phase applications of International applications filed pursuant to 35 USC 371. However, the above-identified application was filed pursuant to 35 USC 111 as a continuation-in-part application of International application PCT/JP03/11248.

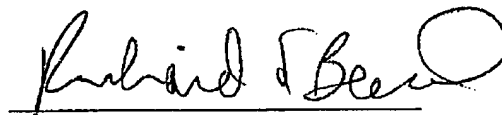
It is submitted that since claims 14 to 16 depend on claims 8 to 10, claims 14 to 16 should be examined along with the other claims of Group II, which include claim 9.

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If the Examiner has any comments, questions, objections or recommendations, the Examiner is invited to telephone the undersigned at the telephone number given below for prompt action.

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Respectfully submitted,



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